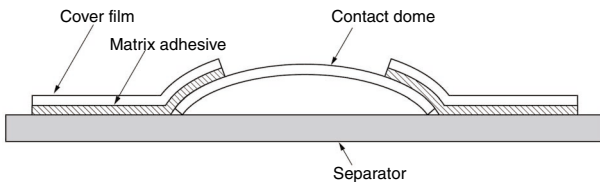
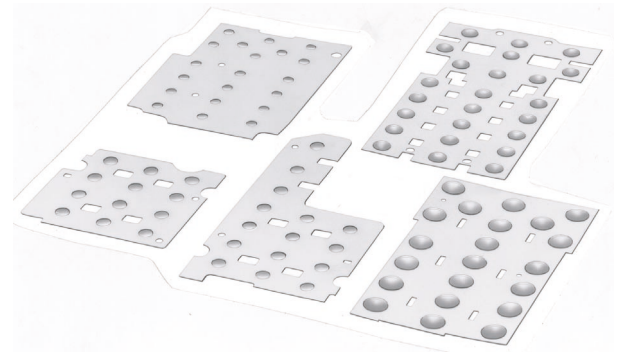


Ultra-low Profile Dome Array

B3DA

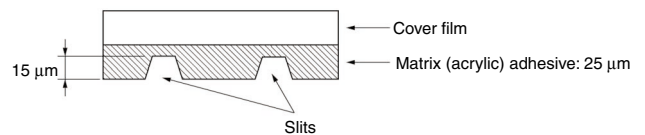
Ultra-low Profile Dome Array with Dust-Proof Construction and Crisp Clicking Action

- Attach directly to PCB to make tactile switch.
- Matrix adhesive used to create highly dust-proof construction with good ventilation.
- Lower profile, lighter weight, and crisp clicking action achieved using stainless steel contact dome.
- Can be designed and produced according to user specifications (e.g., external dimensions or key lay-out).



Matrix Adhesive

This adhesive has grid-shaped slits for ventilation with the structure shown below. The height of the slits is 15 micrometers ensuring both ventilation and dust-proofing.



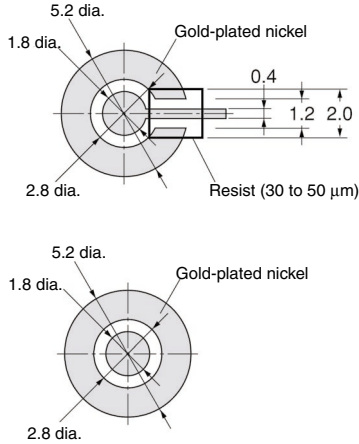
■ Contact Dome Specifications

Item	Specification
Diameter	4-mm dia. and 5-mm dia. models available
Operating force (OF)	1.57 ±0.49 N
Release force (RF)	0.2 N min.
Pretravel (PT)	0.2 ±0.1 mm
Thickness	0.25 ±0.1 mm
Life expectancy	500,000 operations min.
Ambient operating temperature	-40 to 80°C
Ambient storage temperature	-40 to 85°C
Material	Stainless steel
Plating	Unplated, silver

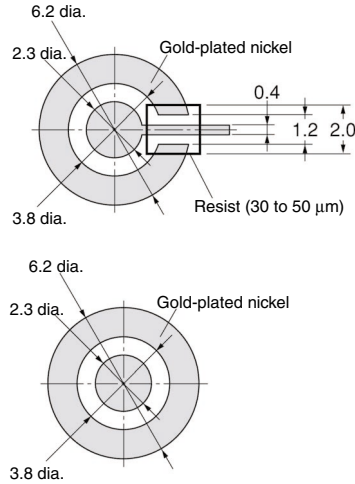
Contact dome specifications not shown in this table are also available.

Recommended Contact Form on PCB

4-mm Diameter Contact Dome

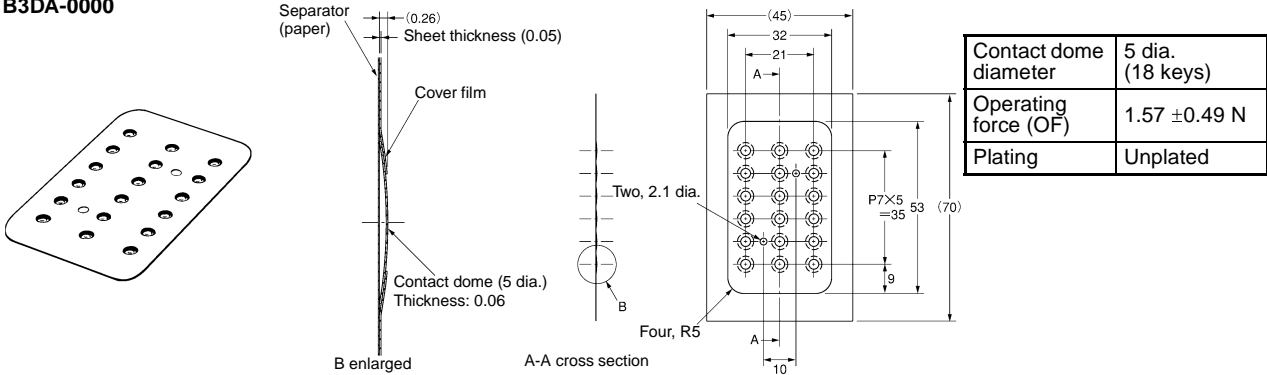


5-mm Diameter Contact Dome

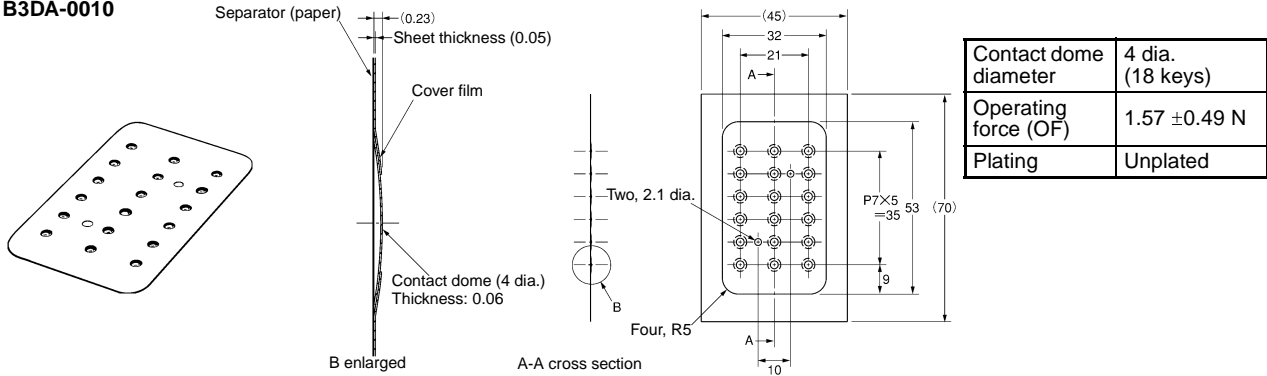


Sample for Reference

B3DA-0000



B3DA-0010



ALL DIMENSIONS SHOWN ARE IN MILLIMETERS.
To convert millimeters into inches, multiply by 0.03937. To convert grams into ounces, multiply by 0.03527.

Cat. No. A121-E1-2 **In the interest of product improvement, specifications are subject to change without notice.**

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